

描述 / Descriptions

SOT-323 塑封封装 PNP 半导体三极管。Silicon PNP transistor in a SOT-323 Plastic Package.

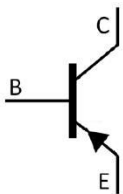
特征 / Features

噪声系数小,与 2SC4081W 互补。
Low noise, complementary pair with 2SC4081W.

用途 / Applications

用于一般小信号放大。
General small signal amplifier applications.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : Emitter PIN 2 : Base PIN 3 : Collector

印章代码 / Marking

h_{FE} Classifications Symbol	Q	R	S
h_{FE} Range	120~270	180~390	270~560
Marking	FHQ	FHR	FHS

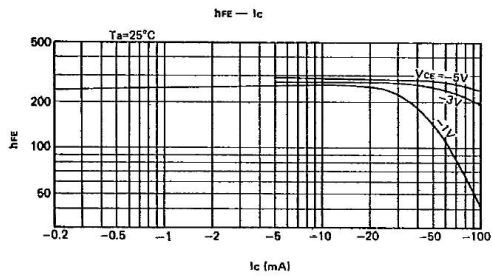
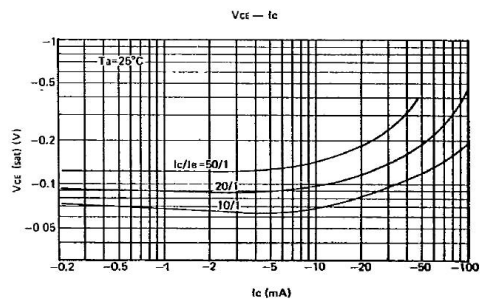
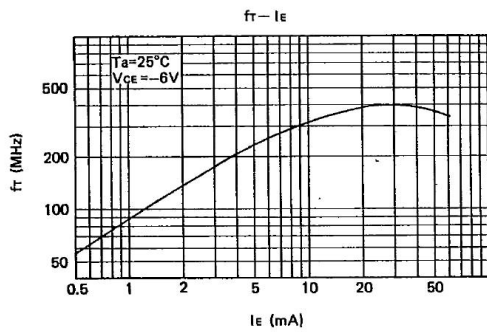
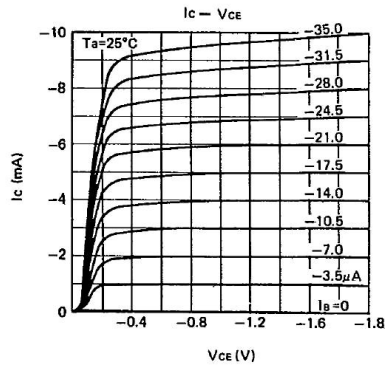
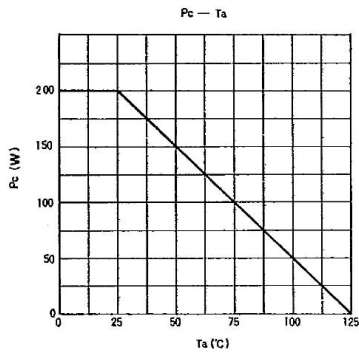
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	-50	V
Collector to Emitter Voltage	V_{CEO}	-40	V
Emitter to Base Voltage	V_{EBO}	-5	V
Collector Current - Continuous	I_C	-100	mA
Collector Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=-50\mu A$ $I_E=0$	-50			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=-1.0mA$ $I_B=0$	-40			V
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E=-50\mu A$ $I_C=0$	-5			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-30V$ $I_E=0$			-0.5	μA
Emitter Base Cut-Off Current	I_{EBO}	$V_{EB}=-4V$ $I_C=0$			-0.5	μA
DC Current Gain	h_{FE}	$V_{CE}=-6V$ $I_C=-1mA$	120		560	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-50mA$ $I_B=-5mA$			-0.5	V
Transition Frequency	f_T	$V_{CE}=-12V$ $I_E=2mA$		140		MHz
Collector output capacitance	C_{ob}	$V_{CB}=-12V$ $f=1.0MHz$ $I_E=0mA$		3.5		pF

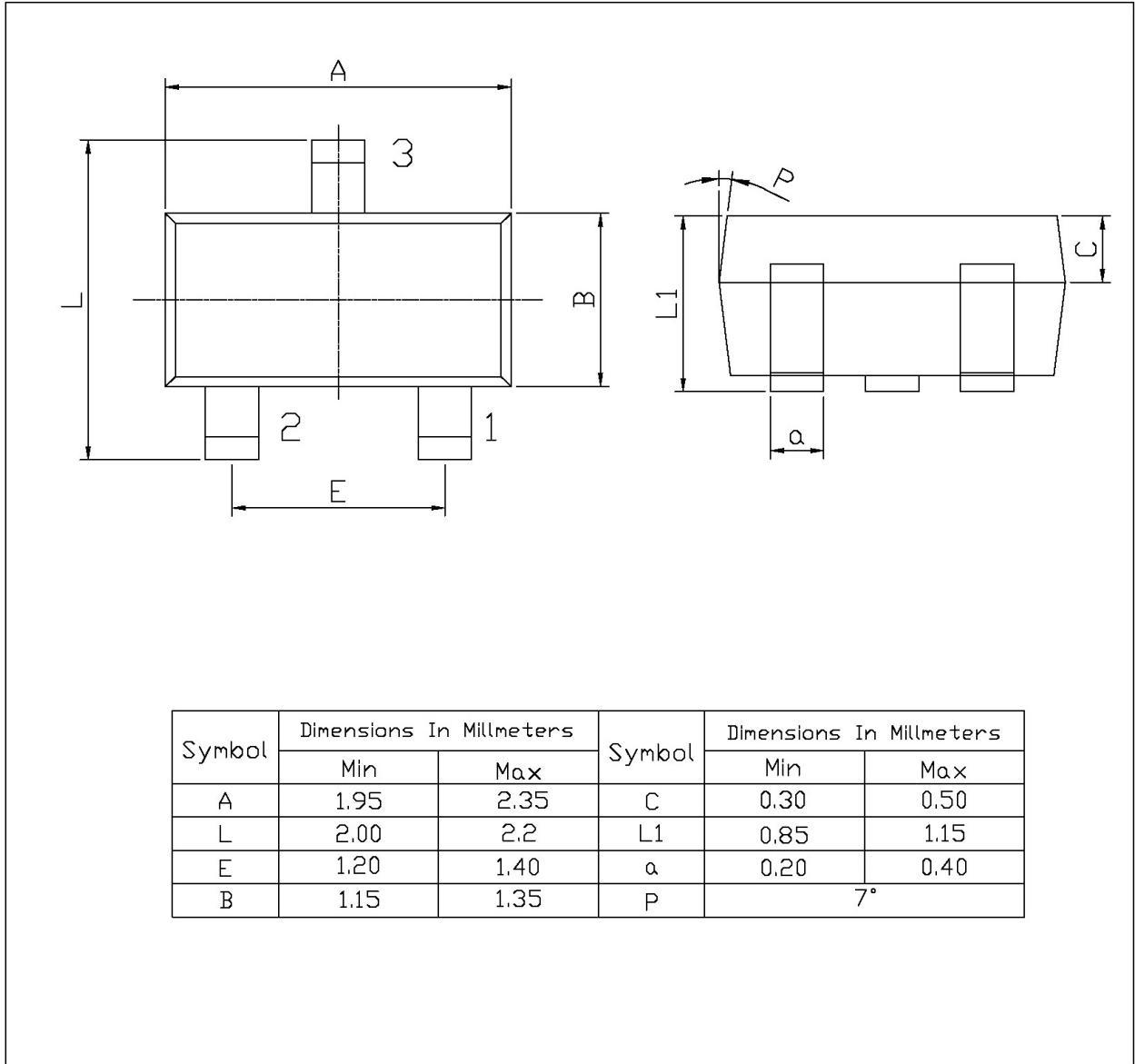
电参数曲线图 / Electrical Characteristic Curve



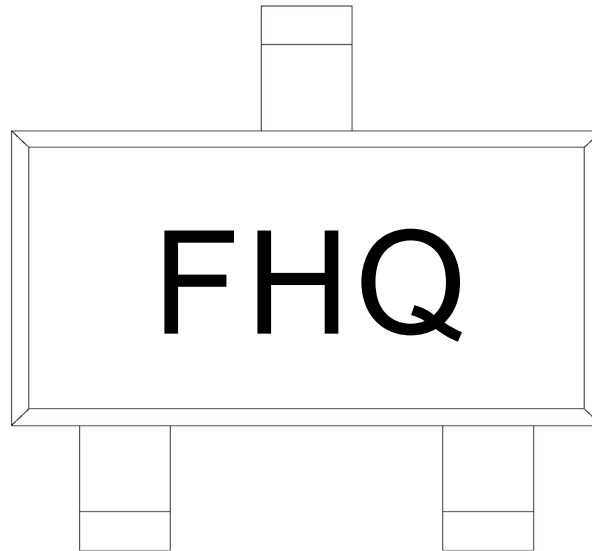
外形尺寸图 / Package Dimensions

SOT-323

单位: mm



印章说明 / Marking Instructions



说明：

- F： 为型号代码
- H： 为公司代码
- Q： 为 h_{FE} 分档代码

Note:

- F: Product Type.
- H: Company Code.
- Q: h_{FE} Classifications Symbol

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-323	3,000	10	30,000	8	240,000	7" x8	180×120×180	385×257×392

使用说明 / Notices